



LightningMaster
Corporation

GROUNDING PLATE COPPER LM-GP-1224



APPLICATION: For use to enhance ground grid systems per NFPA 780 4.13.8.1.1 where topsoil is less than 18" it shall be permitted to provide a ground ring electrode, radials, and/or ground plate electrodes buried at maximum depth of the topsoil available.

DESCRIPTION: 12" X 24" copper ground plate (0.032" thick high conductivity copper sheet with UL 96 listed bonding plate). Available in custom sizes.

Notes:

- Meeting NFPA 780 4.13.6.1 requirements- A ground plate electrode shall have a minimum thickness of 0.032" and a minimum surface area of 2 sq. ft.
- NFPA 780 4.13.6.2 - The ground plate electrode shall be buried no less than 18" below grade.

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